

2018-385 INTELLIGENT FLEXIBLE SPINAL CORD STIMULATORS FOR PAIN AND TRAUMA MANAGEMENT THROUGH NEUROMODULATION

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Technology description

SUMMARY

UCLA researchers in the Department of Neurosurgery and Electrical Engineering have developed a novel closed-loop spinal cord stimulator device that is small and flexible.

BACKGROUND

Over 30 million patients in the US suffer from cervical or neck pain, and the market for neurostimulation is expected to exceed \$2 billion by 2020. Spinal cord stimulation (SCS) therapy consists of embedding devices in the skin above the spinal cord, masking pain signals before they reach the brain. Existing SCS systems only have up to 32 electrodes per square centimeter and utilize complex architectures, with a large battery and many wires and leads. The most common side effect with SCS use is lead migration or breakage and infection; extensive lead migration may require reoperation to position the wires correctly. Additionally, patient response to SCS systems varies greatly, requiring individualized tuning to optimize pain relief.

INNOVATION

Professor Iyer and coworkers have developed a novel SCS device that is small, flexible, and can autonomously adjust stimulation patterns for maximum efficacy. The SCS chip can be easily manufactured using microfabrication technology with a high density of electrodes ($>1000 \text{ cm}^{-2}$), significantly more than existing systems (32 cm^{-2}). Batteries can be embedded onto the device, eliminating the need for leads and wires. Additionally, on-chip machine learning enables the optimization of stimulation patterns based on individual patient and posture for efficacious pain management.

Application area

Treatment of cervical pain

Treatment of neck pain

Neurostimulation

Advantages

>1000 electrodes/cm²

All circuitry located on a single flexible platform

On-chip machine learning will generate personalized stimulation patterns

Device design will eliminate common SCS use side effects

Non-opioid pain management system

Institution

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